

Abstract

The present invention discloses a method for manufacturing an insulated spherical weld gold wire for integrated circuit double-layer stacked package, which relates to the technical field of microelectronic packaging spherical weld gold wires, and specifically comprises the following steps: alloy sheet preparation; alloy rod preparation; stretching; annealing treatment; activation treatment; sputtered insulating coating; multi-winding and sub-packaging, since the polyaryletherketone insulating coating is provided on the surface of the spherical weld gold wire in a scaled integrated circuit and the double-layer stacked package of the present invention, the spherical weld gold wire is allowed to contact and cross during packaging, without affecting the product performance, cost and quality; two high-hardness and high-conductivity materials of cobalt and germanium are added, which greatly enhances the tensile strength of the material.

[Fig. 1]